

ABSTRACT OF THE DISCLOSURE

The flow sensor has a first and a second housing section and a semiconductor chip with an integrated sensor element between the housing sections. The semiconductor chip is arranged at a measuring conduit formed by a groove in a first one of the housing sections. A sealing ring is arranged between the housing sections. A flexible support foil carrying strip conductors is connected to the semiconductor chip and extends between the sealing ring and the second housing section out of the housing. This simple arrangement is able to withstand high pressure.

(Fig. 1)

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